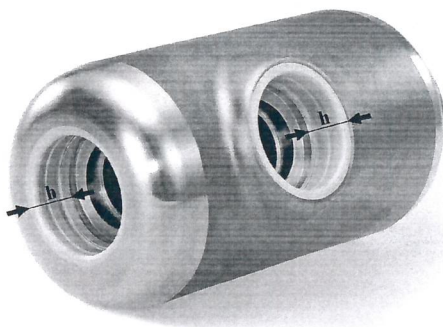


TST Process



Electrotechnical part in aluminium treated with „**TST-Process**“

The process was developed in 1975 especially for plating on aluminium. About twenty years of practice now, tells us that we choose the right way because the output increased rapidly. This technique enables to deposit on aluminium and his alloys, selectively and where you wish, metals as for instance copper, nickel, tin, silver, gold or others.

The process is operated by a device outside the bath, what eliminates the masking job and allows to process parts of unlimited dimensions. Of course this process is also applicable on copper and his alloys as well as on steel and stainless steel. Another advantage is the saving of deposited metal, which cannot be neglected, especially when plating precious metals.

Contrarily to the known "brush-plating" process, where the metal is deposited with an imbibed brush under current, the **TST-process** works without brush, thus obtaining very adherent coatings similar to those obtained with classical electroplating.

In case of aluminium, the deposited copper and silver adhere directly on the deoxidised aluminium.

Therefore the thermal and electrical conductivity corresponds to these of the used aluminium.

Application fields

- High current electrical circuit breaker, where the expensive copper could be replaced by plated aluminium.
- Electrical conductors for high current, where the connecting ends are silver-plated.
- In the SiF₆ technique
- For providing a carted pole on aluminium frames in electronics.
- Extruded aluminium heat sinks are normally used for cooling high power thyristors, triacs and diodes. The difference in electrical potential between heat sink and semiconductor and the tendency of aluminium to oxydize may lead to a degradation of the contact surface. The new **TST-process** has now given a break through and it is possible to plate aluminium with any metal. An excellent adhesion of the plated metal to the aluminium is ensured through complete removing of the oxide layer before plating. Electrical contacts can be soldered directly to the plated surface.
- Heat sinks may be partially plated with round spots of Ni, Sn, Ag or Au what ever the profile length.